

Patent Claims:

1. Printed circuit board (1, 1') comprising strip conductors for electronic circuits and connections for a voltage supply unit being equipped with at least one SMD-component and additional electronic and/or electromechanical parts that are soldered in a suitable manner, said voltage supply unit being connected to one or several supplying strip conductors (2),
characterized in that at least one of the supplying strip conductors (2) includes a break which is bridged in a conductive manner by means of a fuse bridge (6), said fuse bridge (6) containing or being made of a basic material, the melting point of which is lower than the melting point of the material of which the strip conductors are made.
2. Printed circuit board (1, 1') as claimed in claim 1,
characterized in that the melting point of the basic material is equally high or higher than the melting point of the solder used for placement of the printed circuit board (1).
3. Printed circuit board (1, 1') as claimed in claim 1 or 2,
characterized in that the fuse bridge (6) fully consists of metallic material.
4. Printed circuit board (1, 1') as claimed in claim 3,
characterized in that the metallic material contains tin or any tin alloy, or fully consists thereof.

5. Printed circuit board (1, 1') as claimed in any one of claims 1 to 4,
characterized in that the fuse bridge (6) is connected to material of the strip conductor in a conductive fashion by means of the solder used in the soldering process.

6. Printed circuit board (1, 1') as claimed in any one of claims 1 to 5,
characterized in that the fuse bridge (6) is shaped in such a way that it can be fed to a conventional pick-and-place machine in a taped and magazined fashion like a per se known SMD-component.

7. Printed circuit board (1, 1') as claimed in any one of claims 1 to 6,
characterized in that the fuse bridge (6) is manufactured by severing from a wire or a sheet-metal strip.

8. Printed circuit board (1, 1') as claimed in any one of claims 1 to 7,
characterized in that the basic material for manufacturing the fuse bridge (6) is coated with a layer, in particular made of tin, or any tin alloy, or gold, or passivated copper.

9. Printed circuit board (1, 1') as claimed in any one of claims 1 to 8,
characterized in that adjacent supplying strip conductors (2) are separated from each other by recesses (12).

10. Method of manufacturing a printed circuit board (1, 1') as claimed in any one of claims 1 to 9,
characterized in that the fuse bridges (6) are manufactured immediately prior to placement of the printed circuit board (1, 1'), especially by severing from a wire or a sheet-metal strip.